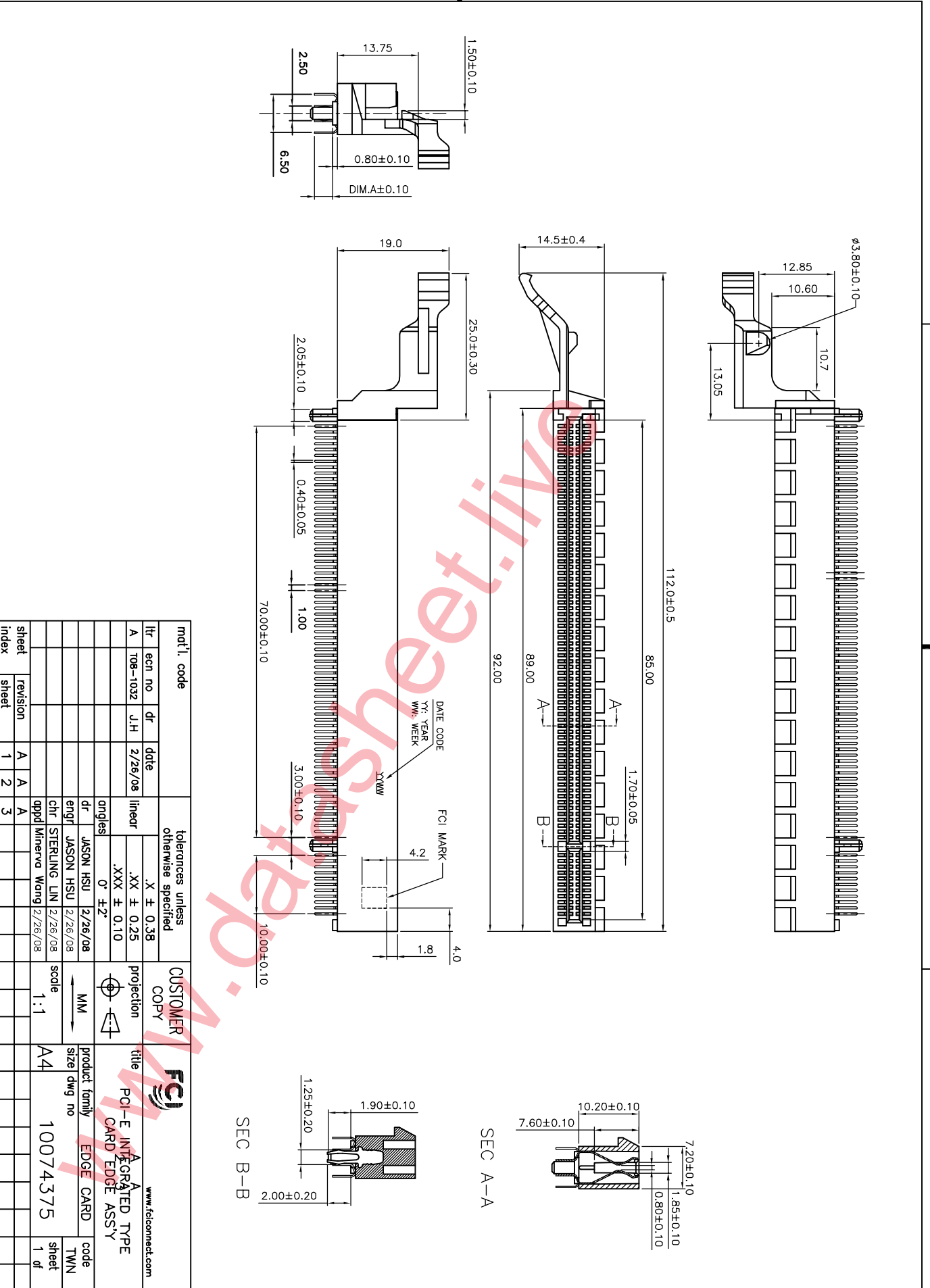




B

A



1 | 2

1 | 2

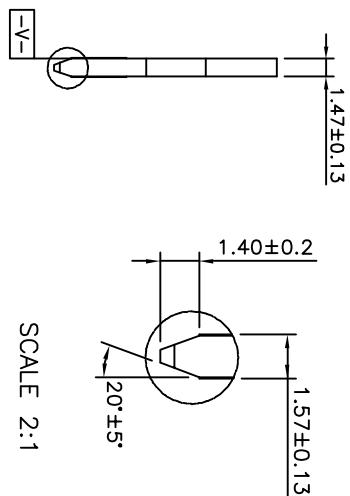
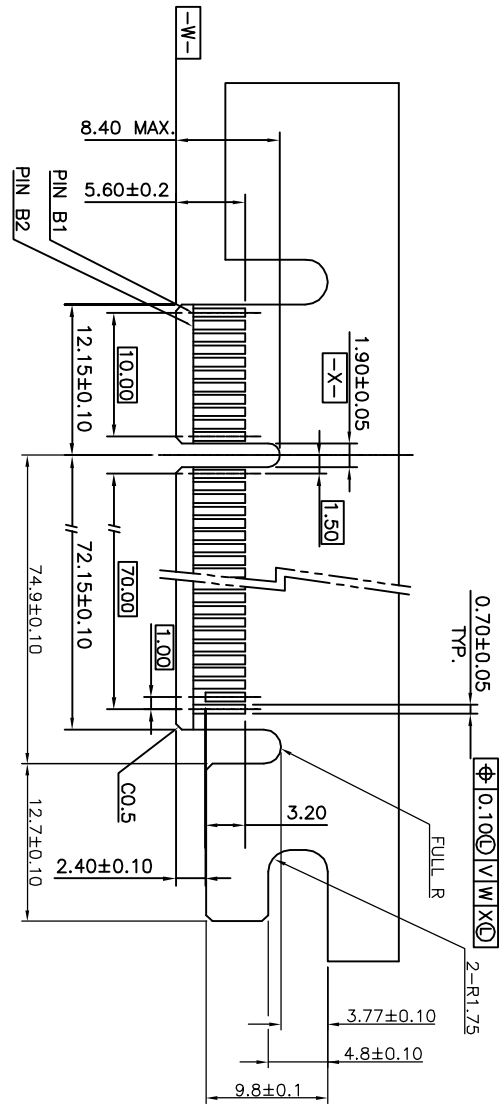
3

3

B

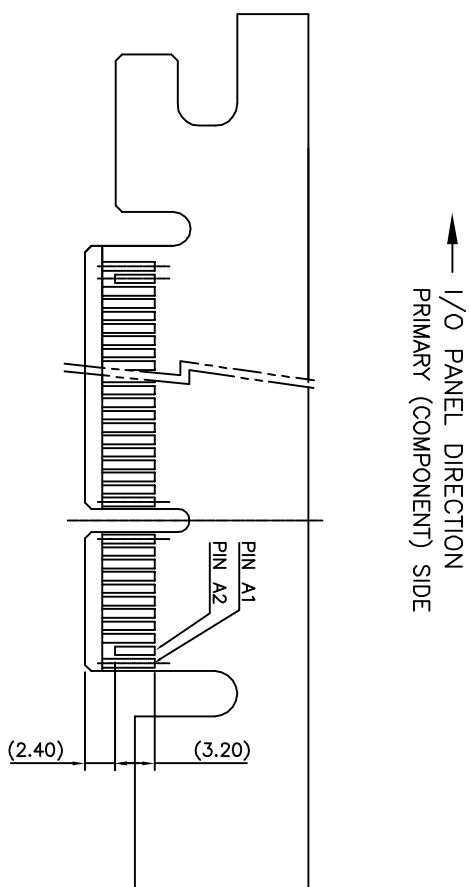
A

| | | | | | | | | | | | | | | |
|--------------------------------------|----------|---------------------------------------|----------|---------------------------|----------|-----------|-----------|--------------|--------------|----------------|----------|----------|----------|-------|
| mat'l. code | | tolerances unless otherwise specified | | CUSTOMER COPY | | FCI | | title | | product family | | code | | |
| itr | ecn no | dr | date | linear | angles | dr | engr | chr | appd | projection | MM | size | dwg no | TWN |
| A | T08-1032 | JH | 2/26/08 | .XX ± 0.25 .XXX ± 0.10 | 0° ± 2° | JASON HSU | JASON HSU | STERLING LIN | Minerva Wang | 1:1 | A4 | 10074375 | 1 of | |
| sheet | revision | sheet | revision | sheet | revision | sheet | revision | sheet | revision | sheet | revision | sheet | revision | sheet |
| 1 | A | 1 | A | 1 | A | 1 | A | 1 | A | 1 | A | 1 | A | 1 |
| ACAD | | | | | | | | | | | | | | |
| cage code | | | | | | | | | | | | | | |
| www.fciconnect.com | | | | | | | | | | | | | | |
| PCI-E INTEGRATED TYPE CARD EDGE ASSY | | | | | | | | | | | | | | |
| EDGE CARD | | | | | | | | | | | | | | |



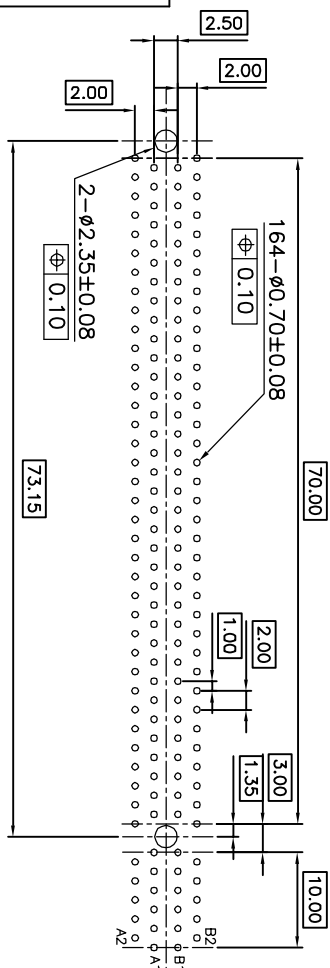
ADD-IN CARD EDGE-FINGER DIMENSIONS

SCALE 2:1



I/O PANEL DIRECTION
SECONDARY (SOLDER) SIDE

RECOMMENDED FOOTPRINT LAYOUT



1 | 2

ACAD

3

4

| | | | | | | | | |
|------------|---------------------------------------|----|---------------|--------|--------------|----------------|--------------|----------------|
| mat'l code | tolerances unless otherwise specified | | CUSTOMER COPY | FCI | title | product family | EDGE CARD | code |
| itr | ecn no | dr | date | linear | .XX ± 0.25 | projection | MM | product family |
| A | | | | angles | 0° ± 2° | chr | STERLING LIN | size dwg no |
| | | | | dr | JASON HSU | appr | Minerva Wang | 10074375 |
| | | | | engr | JASON HSU | date | 2/26/08 | code |
| | | | | chr | STERLING LIN | date | 2/26/08 | TWN |
| | | | | appr | Minerva Wang | date | 2/26/08 | sheet |
| sheet | revision | | | scd | NA | code | A4 | 2 of |
| index | sheet | | | scd | NA | code | A4 | 2 of |

cage code



1 | 2

3

4

NOTES:
1. MATERIAL:
HOUSING: THERMOPLASTIC WITH GLASS FIBER, UL94V-0,
LATCHES: THERMOPLASTIC WITH GLASS FIBER, UL94 HB,
CONTACTS: COPPER ALLOY,
BOARDLOCKS: COPPER ALLOY.

2. FINISH:
CONTACTS: GOLD PLATING ON CONTACT AREA,
100u" MIN. TIN/LEAD OR MATTE TIN (LEAD FREE OPTION) PLATING ON SOLDER TAILS,
50u" MIN. NICKEL UNDERPLATING OVER ALL.

BOARDLOCKS: 100u" MATTE TIN PLATING ON SOLDER TAILS,
50u" MIN. NICKEL UNDERPLATING OVER ALL.

3. WARNING: THE MAXIMUM ALLOWABLE ANGLE TO WITHDRAWAL THE DAUGHTER CARD FROM RETAINER BY 20 DEGREE.

4. DURABILITY: 50 CYCLES.

5. ROHS COMPATIBLE PRODUCT SPECIFICATIONS

a. PLATING: "LF" MEANS THE PRODUCT IS LEAD FREE, 2.5um min. MATTE PURE TIN OVER 1.27um MIN. NICKEL UNDERPLATE.

b. MANUFACTURING PROCESS COMPATIBILITY: THE HOUSING WILL WITHSTAND EXPOSURE TO 260C ±5C SOLDER BATH TEMPERATURE FOR 5 SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.60MM THICK CIRCUIT BOARD.

PRODUCT NUMBER CODE

10074375 -X X X X X X LF

HOUSING COLOR OPTIONS
1-BLACK FOR BASE & RM
2-BLACK FOR BASE & WHITE FOR RM
3-BLUE FOR BASE & RM

PEGS OPTIONS
1-METAL & PLASTIC COMPOUND

TERMINAL PLATING OPTIONS
0-50u" NI UNDERPLATE
30u" AU CONTACT AREA
100u" TIN TAIL AREA
1-50u" NI UNDERPLATE
15u" AU CONTACT AREA
100u" TIN TAIL AREA
2-50u" NI UNDERPLATE
GOLD FLASH CONTACT AREA
100u" TIN TAIL AREA

APPLICATIONS
LF- LEAD FREE

PACKAGING OPTIONS
T-TRAY PACKAGING

POS OPTIONS
3-164

TAIL LENGTH OPTION (DIM A)
1- 3.10MM
2- 2.30MM

| mat'l code | tolerances unless otherwise specified | CUSTOMER COPY | FCI | www.fciconnect.com |
|------------|---------------------------------------|---------------|-----------------------|--------------------|
| thr | .X ± 0.38 | projection | PCI-E INTEGRATED TYPE | code |
| ecr no | .XX ± 0.25 | MM | CARD EDGE ASS'Y | TWN |
| dr | .XXX ± 0.10 | MM | EDGE CARD | sheet |
| linear | 0° ± 2° | MM | 10074375 | 3 of |
| angles | | MM | | |
| dr | JASON HSU 2/26/08 | MM | | |
| engr | JASON HSU 2/26/08 | MM | | |
| chr | STERLING LIN 2/26/08 | MM | | |
| appd | Minerva Wang 2/26/08 | MM | | |
| sheet | | | | |
| revision | | | | |
| index | | | | |

ACAD

1 | 2

3

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